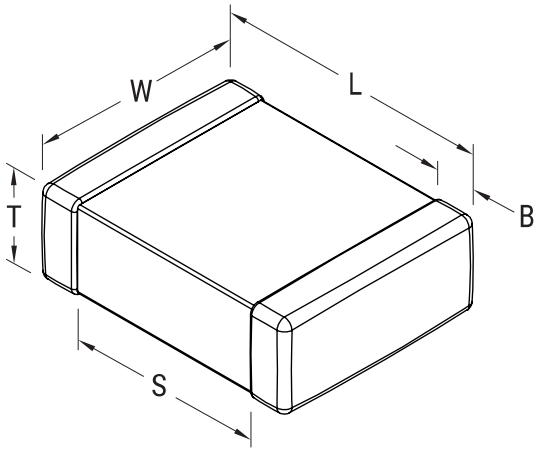
C1206C331F2TAC7210

SMD Comm X8G HT150C, Ceramic, 330 pF, 1%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1206 / 3216



Click here for the 3D model.

General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
Typical Component Weight	15 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
L	3.2mm +/-0.2mm
W	1.6mm +/-0.2mm
T	0.78mm +/-0.10mm
S	1.5mm MIN
B	0.5mm +/-0.25mm
Case Code (EIA / mm)	1206 / 3216

Packaging Specifications	
Packaging	T&R, 330mm, Plastic Tape
Packaging Quantity	10000

Specifications	
Capacitance	330 pF
Measurement Condition	1 MHz 1.0Vrms
Tolerance	1%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1MegaHz 1.0Vrms
Dissipation Factor	0.1% 1 MHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	100 GOhms

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